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RENESAS SEMICONDUCTOR RELIABILITY REPORT

GROUP : RL78/G15

DEVICE : R5F120XXX

APPLICATION : Consumer / Industry

Quality Assurance Div.
Renesas Electronics Corporation

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(Rev.5.0-2 October 2020)

Table. Reliability test results (QFN)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 300 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

*1) With preconditioning per JESD22-A113, MSL 3
・It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :
Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

Table. Reliability test results (LSSOP/SSOP)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 300 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

*1) With preconditioning per JESD22-A113, MSL 3
・It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :
Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

Table. Reliability test results (DFN)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 300 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

*1) With preconditioning per JESD22-A113, MSL 3
・It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :
Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

Table. Reliability test results (SOP)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 300 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500V,1time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL1(Moisture Sensitivity Level 1)	0/22	

*1) With preconditioning per JESD22-A113, MSL 1
・It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :
Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

The failure rate of the device in an actual use condition can be estimated by the below procedure.

・Equation for the failure rate estimation (λ)

$$\lambda = \lambda b \times \pi T \quad (FIT)$$

①Unique failure rate (λb)

λb= 3.8 FIT

Unique failure rate at Ta=55 ℃ using 60 % confidence level.

②Temperature term (πT)

$$\pi T = exp\{11600 \times Ea \times (1/(273+55) - 1/(273+Ta))\}$$

Ea : Activation energy (eV)
Ta : Ambient temperature (℃)

πT simplified chart as Ea=0.7 eV

Ta (℃)	40	50	55	60	65	70	75	80	85	90	100	110
πT	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

・MTTF (Mean Time To Failure)

$$MTTF = 1/\lambda$$

Reference about Renesas package code

Package type		Package code *1
Lead type plastic package	QFP	PxQP
	LSSOP/SSOP/SOP	PxSP
Non-lead type plastic package	QFN	PxQN
	DFN	PxSN
Grid array type plastic package	BGA	PxBG
	LGA	PxLG
Wafer level chip scale package	WLCSP	SxBG

*1. First four digit

Table. Product list

No	Group	Product part number	Package code	No	Group	Product part number	Package code
1	RL78/G15	R5F12067ASP	PLSP0020J*	51			
2	RL78/G15	R5F12067GSP	PLSP0020J*	52			
3	RL78/G15	R5F12067MSP	PLSP0020J*	53			
4	RL78/G15	R5F12068ASP	PLSP0020J*	54			
5	RL78/G15	R5F12068GSP	PLSP0020J*	55			
6	RL78/G15	R5F12068MSP	PLSP0020J*	56			
7	RL78/G15	R5F12017ASP	PLSP0010J*	57			
8	RL78/G15	R5F12017GSP	PLSP0010J*	58			
9	RL78/G15	R5F12017MSP	PLSP0010J*	59			
10	RL78/G15	R5F12018ASP	PLSP0010J*	60			
11	RL78/G15	R5F12018GSP	PLSP0010J*	61			
12	RL78/G15	R5F12018MSP	PLSP0010J*	62			
13	RL78/G15	R5F12047ASP	PRSP0016J*	63			
14	RL78/G15	R5F12047GSP	PRSP0016J*	64			
15	RL78/G15	R5F12047MSP	PRSP0016J*	65			
16	RL78/G15	R5F12048ASP	PRSP0016J*	66			
17	RL78/G15	R5F12048GSP	PRSP0016J*	67			
18	RL78/G15	R5F12048MSP	PRSP0016J*	68			
19	RL78/G15	R5F12047ANA	PWQN0016K*	69			
20	RL78/G15	R5F12047GNA	PWQN0016K*	70			
21	RL78/G15	R5F12047MNA	PWQN0016K*	71			
22	RL78/G15	R5F12048ANA	PWQN0016K*	72			
23	RL78/G15	R5F12048GNA	PWQN0016K*	73			
24	RL78/G15	R5F12048MNA	PWQN0016K*	74			
25	RL78/G15	R5F12008ANS	PWSN0008J*	75			
26	RL78/G15	R5F12008ASN	PRSP0008D*	76			
27	RL78/G15	R5F12008GNS	PWSN0008J*	77			
28	RL78/G15	R5F12008MNS	PWSN0008J*	78			
29	RL78/G15	R5F12008MSN	PRSP0008D*	79			
30	RL78/G15	R5F12007ANS	PWSN0008J*	80			
31	RL78/G15	R5F12007GNS	PWSN0008J*	81			
32	RL78/G15	R5F12007MNS	PWSN0008J*	82			
33				83			
34				84			
35				85			
36				86			
37				87			
38				88			
39				89			
40				90			
41				91			
42				92			
43				93			
44				94			
45				95			
46				96			
47				97			
48				98			
49				99			
50				100			